MA3XD17

Silicon epitaxial planar type

For high frequency rectification

■ Features

- $V_R = 100 \text{ V}$ is guaranteed
- Mini type 3-pin package

■ Absolute Maximum Ratings $T_a = 25$ °C

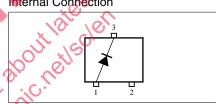
Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	100	V
Peak reverse voltage	V_{RM}	100	V
Non-repetitive peak forward- surge-current *	I_{FSM}	1.5	A
Average forward current	I _{F(AV)}	300	mA
Junction temperature	T _j	125	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M5K

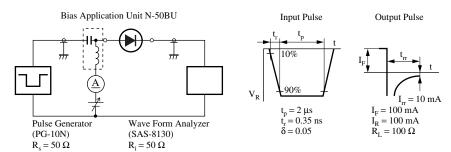
Internal Connection



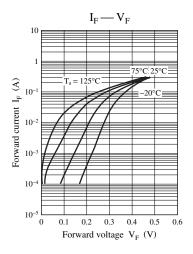
■ Electrical Characteristics T_a = 25°C ± 3°C

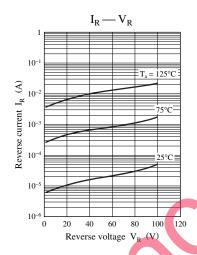
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current (DC)	I_R	$V_R = 100 V$			200	μΑ
Forward voltage (DC)	$V_{\rm F}$	$I_{\rm F} = 300 \text{ mA}$		0.50	0.58	V
Terminal capacitance	C _t	$V_R = 0$ V, $f = 1$ MHz		100		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		7		ns
	0,	$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

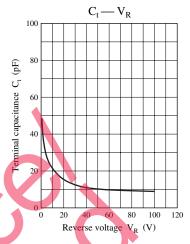
- Note) 1. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 2. Rated input/output frequency: 250 MHz 3. *: t_{rr} measuring instrument



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